



General Undergraduate Scholarship Application

A. Eligibility Requirements

- Financial need, as determined by the Financial Aid Office through the Free Application for Federal Student Aid, is a criteria for most SET scholarships. Submit a FAFSA for the upcoming academic year: www.fafsa.ed.gov.
- Demonstrate a cumulative GPA of 3.2 or above.
- Must be admitted into one of the School of Engineering & Technology degree programs.

B. Application Components

A complete application packet will include:

- Application form (see next page)
- Professional or Academic Recommendation
- A resume including service or leadership activities for your college campus and/or local community
- **Personal statement:** The essay should address how your service or leadership activities have enhanced your campus, local community and/or yourself academically, professionally, and personally. Specifically identify evidence of improvement and motivation as a result of this involvement and discuss how you intend to continue service after graduation. Essays must be attached to the application form. The essay should be typed, double-spaced, and one (minimum) to two pages in length. ****Please no more than two pages in length.****

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C. Applicant Information

Name _____ Student ID _____
Address _____ Zip Code _____ Phone _____
Email _____ Undergraduate Program: ITS CSCI CES EE
 New Student Continuing Student
Expected Enrollment Full time Part time
Expected Graduation Quarter: _____ Year: _____
Apply Scholarship to: Aut Win Spr

Will you be receiving tuition funding from your employer? No
 Yes If yes, how much: _____

D. Professional/Faculty Recommendation

List information for the individual providing your recommendation. Submit the recommendation with all other required documentation.

Recommender _____
Title or Position _____
Relationship _____
Email _____ Phone _____

E. Attachments

All documentation must be submitted and attached to this application in one complete packet, see section B for complete list.

F. Signature

I understand that any portion of this application may be released to the public should I be offered and accept this award. Information provided will become the property of the School of Engineering & Technology and the University of Washington and will not be returned. Ranking of applicants will not be disclosed.

Please print and sign the application form to include with your scholarship application packet.

Applicant Signature _____ Date _____

Incomplete application packets will not be considered.

University of Washington, Tacoma
School of Engineering & Technology
Attn: Scholarship Committee
Campus Box 358426
1900 Commerce St.
Tacoma, WA 98402